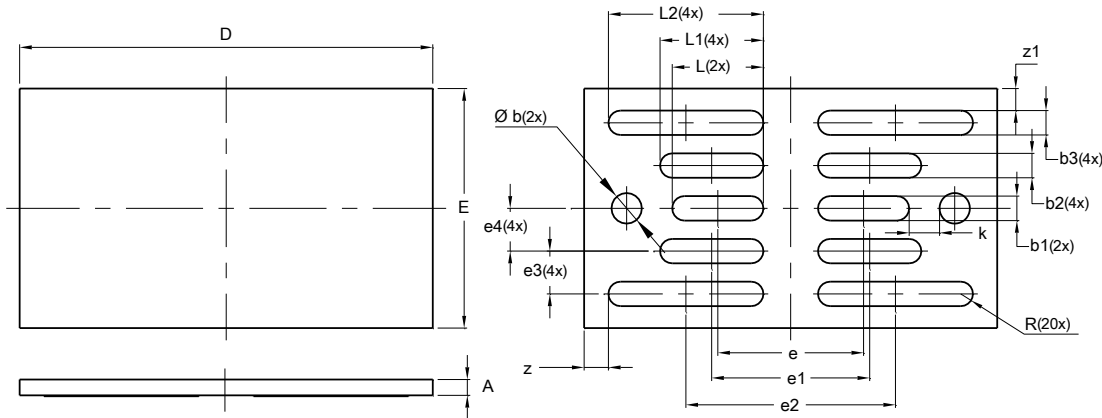


Package Outline Dimensions

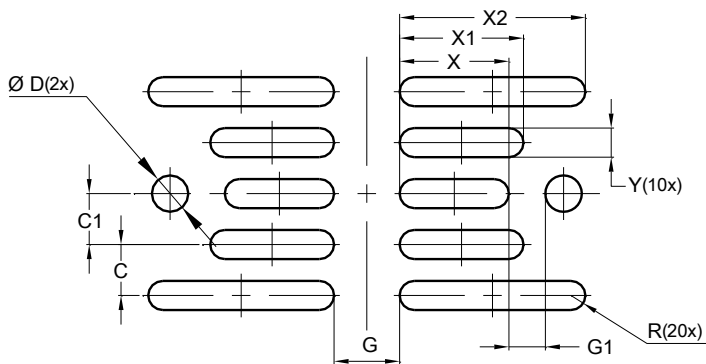
X4-DSN3420-12



X4-DSN3420-12			
Dim	Min	Max	Typ
A	0.05	0.150	0.100
b	0.220	0.280	0.250
b1	0.170	0.230	0.200
b2	0.170	0.230	0.200
b3	0.170	0.230	0.200
D	3.37	3.44	3.40
E	1.93	2.00	1.96
e	1.200BSC		
e1	1.300BSC		
e2	1.725BSC		
e3	0.350BSC		
e4	0.350BSC		
k	0.250BSC		
L	0.720	0.780	0.750
L1	0.820	0.880	0.850
L2	1.245	1.305	1.275
R	--	--	0.100
z	--	--	0.200
z1	--	--	0.180
All Dimensions in mm			

Suggested Pad Layout

X4-DSN3420-12



Dimensions	Value (in mm)
C	0.350
C1	0.350
D	0.250
G	0.450
G1	0.250
X	0.750
X1	0.850
X2	1.275
Y	0.200
R	0.100

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.